

ABSTRACT

A method and apparatus for providing double-sided cooling of leadframe-based wire-bonded electronic packages. The method includes the steps of: positioning a plurality of heatslug members (140) over a corresponding plurality of electronic packages (100') formed on a leadframe strip (142), wherein each of the heatslug members includes a heatslug (130) and a plurality of legs (144) for supporting the heatslug over a respective one of the electronic packages; introducing a molding compound (132) between each heatslug member and its respective electronic package; curing the molding compound; and cutting the heatslug members and separating the electronic packages (100) from the leadframe strip, such that each electronic package includes a heatslug for cooling a first side of the electronic package.